ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES® INDUSTRIES®	nnockburn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration er	on of the sub compasses	bstances w all lower	vithin the manufactur level materials for wl	er listed it hich the m	em. Note: if anufacturer	the item is an as the engineering	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat					on		
Supplier Information												
mpany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi									2024-04-25			
Contact Name	Title - Contact			]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*	horized Representative* Title - Representative			]	Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Requester Item Number N	Ifr Item Number	Afr Item Name			Effective Date	Version	М	lanufacturing Site	V	Veight*	UOM	Unit Type
	VMFS5C410NLWF 3G				2024-04-25 N		М	MY1		07.2528	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base A	Terminal Base Alloy J-S'		Rating	Peak Process Body Tempera		mperature	ure Max Time at Peak Temper		ire Numb	er of Reflow Cyc	eles
Matte Tin (Sn) - annealed CU Alloy 1		1		260		С	30	second	ls 3			
Comments												
level 1 - maximum time at peak temperature du	ring soldering is 10-3	0 seconds										
For more information regarding material comp	osition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	13.512	mg	Supplier	Zinc (Zn)	7440-66-6		0.0162	mg
			Supplier	Iron (Fe)	7439-89-6		0.3175	mg
			Supplier	Copper (Cu)	7440-50-8		13.1742	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0041	mg
Die	0.727	mg	Supplier	Silicon (Si)	7440-21-3		0.727	mg
Die Attach Solder	1.4993	mg	Supplier	Silver (Ag)	7440-22-4		0.0375	mg
			А	Lead (Pb)	7439-92-1	7a	1.3869	mg
			Supplier	Tin (Sn)	7440-31-5		0.075	mg
Lead Frame	42.5398	mg	Supplier	Silver (Ag)	7440-22-4		0.0255	mg
			Supplier	Iron (Fe)	7439-89-6		0.0425	mg
			Supplier	Copper (Cu)	7440-50-8		42.459	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0128	mg
Mold Compound-Black	48.7198	mg		Epoxy resin	proprietary data		3.654	mg
			Supplier	Phenolic Resin	Proprietary Data		1.218	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.654	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2436	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9502	mg
Plating	0.2183	mg	Supplier	Tin (Sn)	7440-31-5		0.2183	mg
Wire Bond - Cu	0.0366	mg	Supplier	Copper (Cu)	7440-50-8		0.0366	mg